Black ink only

TERADYNE
Release

Release Form
☐ Pre-production
☑ Production DEC 2 0 2004
☐ Multiple PNs Continuation Form attached

Release Number
R21279.8

Part Number Affected | **Hierarchy Bom** ☐
705-099-00

Standards Description																			**Distribution Date** FEB 14 2005
F|P|G|A| S|M|C| N|O|D|E| Q|L|3|0|1|2																			

Full Description

SMC FPGA NODE CODE QL3012

First Article Checklist	Yes	No	N/A	Engineer
Open Issues, including First Article Checklist (FAC) items?			X	R.M.
First Article Checklist and design information archived?			X	R.M.
Controlled Documents			X	Revision
Revision Stamp				
Bill of Materials				
PCB Aw Pkg/Fab Dwg				
Schematic				
Piece Part Drawing				
Assembly Drawing				
Wire List				
Component Spec.				
Process/Tool Spec.				
Test Procedure				
MRP Revision			X	001
Firmware Source Code			X	2CE7EE
Software				

Final copies of all applicable controlled documents must be attached to this release (as required).

Complete path to Drawings or PC board files:

Originator Ruben Monreal | **Ext.** 7501
Signature | Date

Approvers
Name	Karen McElfresh	Ext. 7779
Signature	Karen McElf	Date 12/17/04
Name		Ext.
Signature		Date
Name		Ext.
Signature		Date
Name		Ext.
Signature		Date

Organization ICD

Type of Part
⦿ Piece Part or Purchased Assy
○ Outsourced Assembly
○ Manufactured Assembly

Product Family (System Type)
JAGUAR (CORE)

Estimated Unit Cost $0

Approved Effectivity (PCBs only)

Control Point	Implementation Week	Unit Number
Purchasing		
MRP		
Stockroom		
Production		
Stage		
Final Test		
GCS Returns		

Additional Names for Distribution
NPI Bomsnd

Additional information, implementation restrictions | ☐ BOM Creation Continuation Form attached | ☐ Update PCB Ship Rev File

Program Name: SMC_fpga-d2.chp

Program file located at:
Platform/Services/smcSCV/PantherSMC/psd   Check Sum: 2ce7ee

Blank Teradyne Part Number 438-978-02

SEMICONDUCTOR TEST DIVISION

FEB 14 2005   0507

PROCESSED ENGINEERING SERVICES

STD Form **9245C** (Rev. 0449)